Title (en)

METHOD FOR HANDLING THINNED CHIPS FOR INTRODUCING THEM INTO CHIP CARDS

Title (de)

VERFAHREN ZUM HANDHABEN VON GEDÜNNTEN CHIPS ZUM EINBRINGEN IN CHIPKARTEN

Title (fr)

PROCEDE DE MANIPULATION DE PUCES AMINCIES POUR LE DEPOT DESDITES PUCES SUR DES CARTES A PUCE

Publication

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Application

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Abstract (en)

[origin: DE19921230A1] The invention relates to a method for handling thinned chips for introducing them into chip cards. According to the inventive method, first a wafer is bonded with its front face onto a carrier substrate by means of an adhesive layer. Then the wafer is thinned from its back and is subdivided into single chips by sawing into the wafer from the back up to the adhesive layer. The adhesive layer is dissolved and the individual chips are removed from the carrier substrate by means of a suction head and are deposited in a special storage container until further treatment. Alternatively, the chips sawed out from the wafer are provided on their backs with a continuous support film by means of a second adhesive layer and the first adhesive layer is dissolved by means of a method that does not attack the second adhesive layer. The chips that are linked via the support film can be jointly removed from the carrier substrate and can be removed form the support film one by one once the second adhesive layer is removed. The wafer can alternatively be provided with a continuous support film by means of a second adhesive layer before it is sawed from the back. In this case, too, the first adhesive layer is dissolved while the second adhesive layer is conserved and the individual chips that are reinforced by the support film are removed from the carrier substrate.

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H01L 21/78; H01L 21/52

IPC 8 full level

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